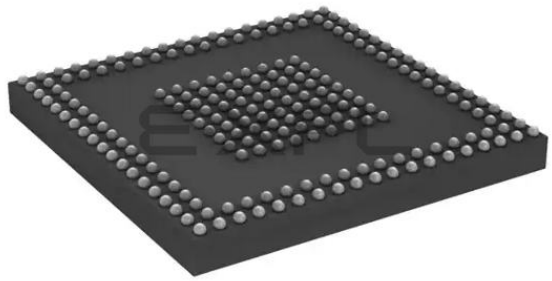

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	XCore
Core Size	32-Bit 10-Core
Speed	800MIPS
Connectivity	Configurable
Peripherals	-
Number of I/O	90
Program Memory Size	128KB (32K x 32)
Program Memory Type	SRAM
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	0.90V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	217-LFBGA
Supplier Device Package	217-FBGA (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/xmos/xs1-a10a-128-fb217-i8

- **Channels and channel ends** Tasks running on logical cores communicate using channels formed between two channel ends. Data can be passed synchronously or asynchronously between the channel ends assigned to the communicating tasks. Section 7.5
- **xCONNECT Switch and Links** Between tiles, channel communications are implemented over a high performance network of xCONNECT Links and routed through a hardware xCONNECT Switch. Section 7.6
- **Ports** The I/O pins are connected to the processing cores by Hardware Response ports. The port logic can drive its pins high and low, or it can sample the value on its pins optionally waiting for a particular condition. Section 7.3
- **Clock blocks** xCORE devices include a set of programmable clock blocks that can be used to govern the rate at which ports execute. Section 7.4
- **Memory** Each xCORE Tile integrates a bank of SRAM for instructions and data, and a block of one-time programmable (OTP) memory that can be configured for system wide security features. Section 10
- **PLL** The PLL is used to create a high-speed processor clock given a low speed external oscillator. Section 8
- **JTAG** The JTAG module can be used for loading programs, boundary scan testing, in-circuit source-level debugging and programming the OTP memory. Section 14

1.1 Software

Devices are programmed using C, C++ or xC (C with multicore extensions). XMOS provides tested and proven software libraries, which allow you to quickly add interface and processor functionality such as USB, Ethernet, PWM, graphics driver, and audio EQ to your applications.

1.2 xTIMEcomposer Studio

The xTIMEcomposer Studio development environment provides all the tools you need to write and debug your programs, profile your application, and write images into flash memory or OTP memory on the device. Because xCORE devices operate deterministically, they can be simulated like hardware within xTIMEcomposer: uniquely in the embedded world, xTIMEcomposer Studio therefore includes a static timing analyzer, cycle-accurate simulator, and high-speed in-circuit instrumentation.

xTIMEcomposer can be driven from either a graphical development environment, or the command line. The tools are supported on Windows, Linux and MacOS X and available at no cost from xmos.com/downloads. Information on using the tools is provided in the xTIMEcomposer User Guide, X3766.

6 Product Overview

The XS1-A10A-128-FB217 comprises a digital and an analog node, as shown in Figure 3. The digital node comprises an xCORE Tile, a Switch, and a PLL (Phase-locked-loop). The analog node comprises a multi-channel ADC (Analog to Digital Converter), deep sleep memory, an oscillator, a real-time counter, and power supply control.

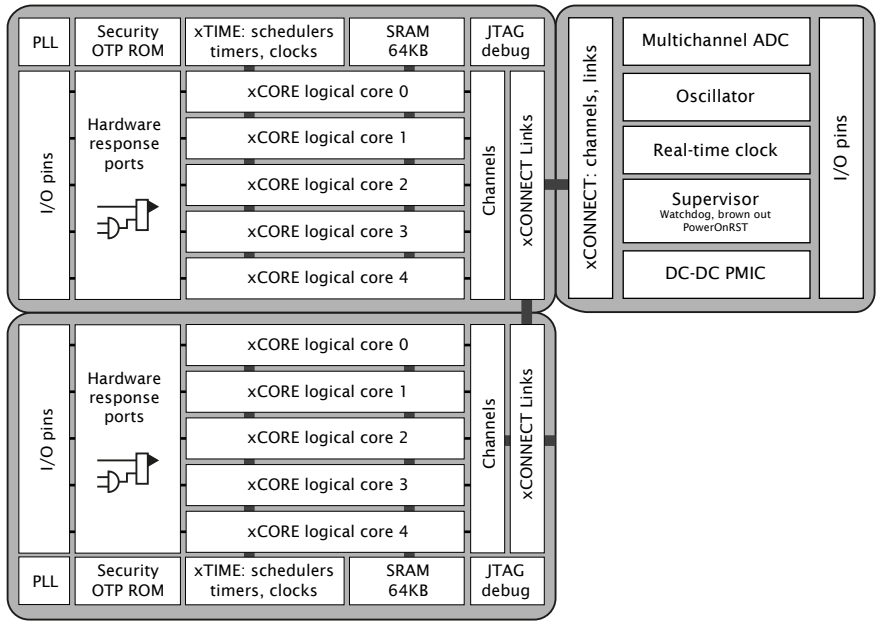

Figure 3: Block Diagram

All communication between the digital and analog node takes place over a link that is connected to the Switch of the digital node. As such, the analog node can be controlled from any node on the system. The analog functions can be configured using a set of node configuration registers, and a set of registers for each of the peripherals.

The device can be programmed using high-level languages such as C/C++ and the XMOS-originated XC language, which provides extensions to C that simplify the control over concurrency, I/O and timing, or low-level assembler.

6.1 XCore Tile

The xCORE Tile is a flexible multicore microcontroller component with tightly integrated I/O and on-chip memory. The tile contains multiple logical cores that run simultaneously, each of which is guaranteed a slice of processing power and can execute computational code, control software and I/O interfaces. The logical cores use channels to exchange data within a tile or across tiles. The tiles are connected via an integrated switch network, called xCONNECT, which uses a

rising edge of the sample pin the ADC samples, holds and converts the data value from one of the analog input pins. Each of the 8 inputs can be enabled individually. Each of the enabled analog inputs is sampled in turn, on successive rising edges of the sample pin. The data is transmitted to the channel-end that the user configures during initialization of the ADC. Data is transmitted over the channel in individual packets, or in packets that contain multiple consecutive samples. The ADC uses an external reference voltage, nominally 3V3, which represents the full range of the ADC. The ADC configuration registers are documented in Appendix F.

The minimum latency for reading a value from the ADC into the xCORE register is shown in Figure 13:

Figure 13: Minimum latency to read sample from ADC to xCORE

Sample	Tile clock frequency	Start of packet	Subsequent samples
32-bit	500 MHz	840 ns	710 ns
32-bit	400 MHz	870 ns	740 ns
16-bit	500 MHz	770 ns	640 ns
16-bit	400 MHz	800 ns	670 ns

12 Supervisor Logic

An independent supervisor circuit provides power-on-reset, brown-out, and watchdog capabilities. This facilitates the design of systems that fail gracefully, whilst keeping BOM costs down.

The reset supervisor holds the chip in reset until all power supplies are good. This provides a power-on-reset (POR). An external reset is optional and the pin RST_N can be left not-connected.

If at any time any of the power supplies drop because of too little supply or too high a demand, the power supervisor will bring the chip into reset until the power supplies have been restored. This will reboot the system as if a cold-start has happened.

The 16-bit watchdog timer provides 1ms accuracy and runs independently of the real-time counter. It can be programmed with a time-out of between 1 ms and 65 seconds (Appendix E). If the watchdog is not set before it times out, the XS1-A10A-128-FB217 is reset. On boot, the program can read a register to test whether the reset was due to the watchdog. The watchdog timer is only enabled and clocked whilst the processor is in the AWAKE power state.

13 Energy management

XS1-A10A-128-FB217 devices can be powered by:

- An external 5v core and 3.3v I/O supply.
- A single 3.3v supply.

13.3 Deep Sleep Modes and Real-Time Counter

The normal mode in which the XS1-A10A-128-FB217 operates is the AWAKE mode. In this mode, all cores, memory, and peripherals operate as normal. To save power, the XS1-A10A-128-FB217 can be put into a deep sleep mode, called ASLEEP, where the digital node is powered down, and most peripherals are powered down. The XS1-A10A-128-FB217 will stay in the ASLEEP mode until one of two conditions:

1. An external pin is asserted or deasserted (set by the program);

2. The 64-bit real-time counter reaches a value set by the program; or

When the chip is awake, the real-time counter counts the number of clock ticks on the oscillator. As such, the real-time counter will run at a fixed ratio, but synchronously with the 100 MHz timers on the xCORE Tile. When asleep, the real-time counter can be automatically switched to the 31,250 Hz silicon oscillator to save power (see Appendix H). To ensure that the real-time counter increases linearly over time, a programmable value is added to the counter on every 31,250 Hz clock-tick. This means that the clock will run at a granularity of 31,250 Hz but still maintain real-time in terms of the frequency of the main oscillator. If an accurate clock is required, even whilst asleep, then an external crystal or oscillator shall be provided that is used in both AWAKE and ASLEEP state.

The designer has to make a trade-off between accuracy of clocks when asleep and awake, costs, and deep-sleep power consumption. Four example designs are shown in Figure 15.

Figure 15: Example trade-offs in oscillator selection

Clocks used		Power	BOM	Accuracy	
Awake	Asleep	Asleep	costs	Awake	Asleep
20 Mhz SiOsc	31,250 SiOsc	lowest	lowest	lowest	lowest
24 MHz Crystal	31,250 SiOsc	lowest	medium	highest	lowest
5 MHz ext osc	5 MHz ext osc	medium	highest	highest	highest
24 MHz Crystal	24 MHz crystal	highest	medium	highest	highest

During deep-sleep, the program can store some state in 128 bytes of Deep Sleep Memory.

13.4 Requirements during sleep mode

Whilst in sleep mode, the device must still be powered as normal over 3V3 or 5V0 on VSUP, and 3V3 on VDDIO; however it will draw less power on both VSUP and VDDIO.

For best results (lowest power):

- The XTAL bias and XTAL oscillators should be switched off.
- The sleep register should be configured to

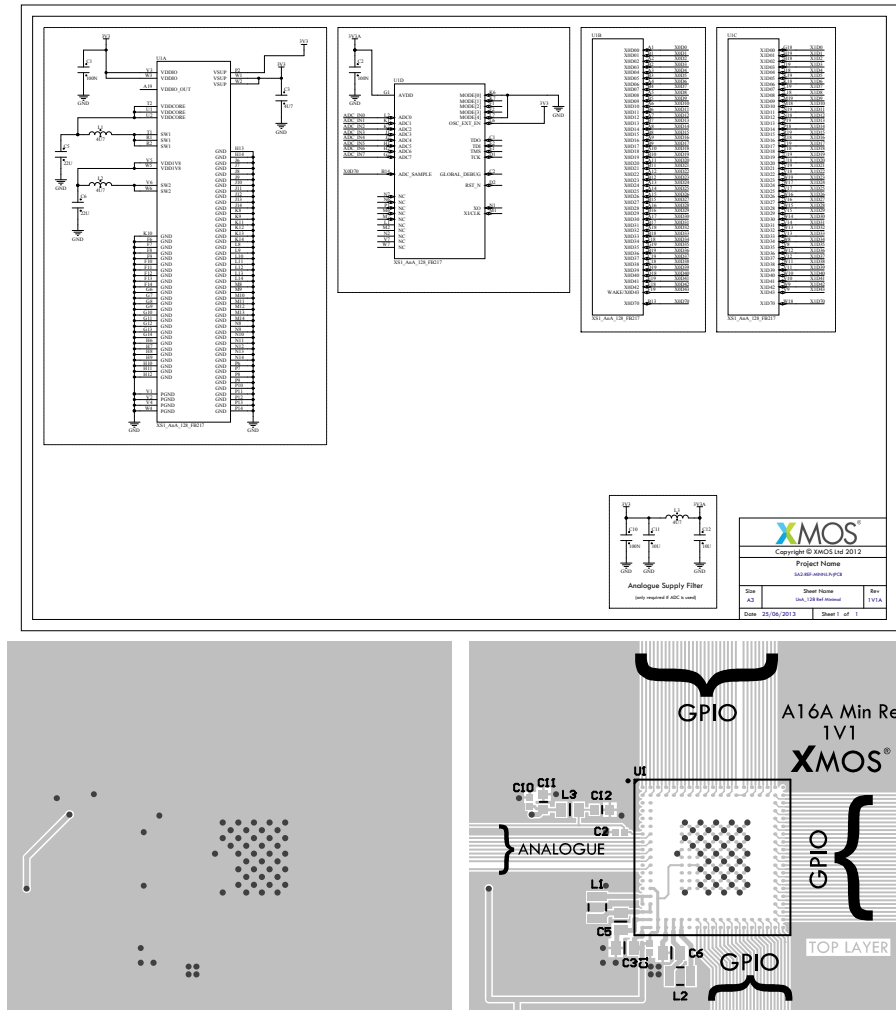

Figure 23: Example minimal system schematic, with top and bottom layout of a 2-layer PCB

17.5 Digital I/O Characteristics

Figure 28: Digital I/O characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
V(IH)	Input high voltage	2.00		3.60	V	A
V(IL)	Input low voltage	-0.30		0.70	V	A
V(OH)	Output high voltage	2.00			V	B, C
V(OL)	Output low voltage			0.60	V	B, C
R(PU)	Pull-up resistance		35K		Ω	D
R(PD)	Pull-down resistance		35K		Ω	D

A All pins except power supply pins.

B Ports 1A, 1D, 1E, 1H, 1I, 1J, 1K and 1L are nominal 8 mA drivers, the remainder of the general-purpose I/Os are 4 mA.

C Measured with 4 mA drivers sourcing 4 mA, 8 mA drivers sourcing 8 mA.

D Used to guarantee logic state for an I/O when high impedance. The internal pull-ups/pull-downs should not be used to pull external circuitry.

17.6 ESD Stress Voltage

Figure 29: ESD stress voltage

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
HBM	Human body model			2.00	kV	
CDM	Charged Device Model			500	V	

17.7 Device Timing Characteristics

Figure 30: Device timing characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
T(RST)	Reset pulse width	5			µs	
T(INIT)	Initialisation (On Silicon Oscillator)			TBC	ms	A
	Initialisation (Crystal Oscillator)			TBC	ms	
T(WAKE)	Wake up time (Sleep to Active)			TBC	ms	
T(SLEEP)	Sleep Time (Active to Sleep)			TBC	ms	

A Shows the time taken to start booting after RST_N has gone high.

17.8 Crystal Oscillator Characteristics

Figure 31: Crystal oscillator characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
F(FO)	Input Frequency	5		30	MHz	

17.9 External Oscillator Characteristics

Figure 32: External oscillator characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
F(EXT)	External Frequency			100	MHz	
V(IH)	Input high voltage	1.62		1.98	V	
V(IL)	Input low voltage			0.4	V	

17.10 Power Consumption

Figure 33: xCORE Tile currents

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
P(AWAKE)	Active Power for awake states (Speed Grade 10)	TBC	600	TBC	mW	
	Active Power for awake states (Speed Grade 8)	TBC	480	TBC	mW	
P(SLEEP)	Power when asleep	TBC	500	TBC	µW	

17.11 Clock

Figure 34: Clock

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
f(MAX)	Processor clock frequency (Speed Grade 10)			500	MHz	A
	Processor clock frequency (Speed Grade 8)			400	MHz	A

A Assumes typical tile and I/O voltages with nominal activity.

17.12 Processor I/O AC Characteristics

Figure 35: I/O AC characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
T(XOVALID)	Input data valid window	8			ns	
T(XOINVALID)	Output data invalid window	9			ns	
T(XIFMAX)	Rate at which data can be sampled with respect to an external clock			60	MHz	

The input valid window parameter relates to the capability of the device to capture data input to the chip with respect to an external clock source. It is calculated as the sum of the input setup time and input hold time with respect to the external clock as measured at the pins. The output invalid window specifies the time for which an output is invalid with respect to the external clock. Note that these parameters are specified as a window rather than absolute numbers since the device provides functionality to delay the incoming clock with respect to the incoming data.

Information on interfacing to high-speed synchronous interfaces can be found in the XS1 Port I/O Timing document, X5821.

17.13 xConnect Link Performance

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
B(2blinkP)	2b link bandwidth (packetized) (Speed Grade 10)			103	MBit/s	A, B
	2b link bandwidth (packetized) (Speed Grade 8)			82	MBit/s	A, B
B(5blinkP)	5b link bandwidth (packetized) (Speed Grade 10)			271	MBit/s	A, B
	5b link bandwidth (packetized) (Speed Grade 8)			215	MBit/s	A, B
B(2blinkS)	2b link bandwidth (streaming) (Speed Grade 10)			125	MBit/s	B
	2b link bandwidth (streaming) (Speed Grade 8)			100	MBit/s	B
B(5blinkS)	5b link bandwidth (streaming) (Speed Grade 10)			313	MBit/s	
	5b link bandwidth (streaming) (Speed Grade 8)			250	MBit/s	B

Figure 36: Link performance

A Assumes 32-byte packet in 3-byte header mode. Actual performance depends on size of the header and payload.

B 7.5 ns symbol time.

The asynchronous nature of links means that the relative phasing of CLK clocks is not important in a multi-clock system, providing each meets the required stability criteria.

17.14 JTAG Timing

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
f(TCK_D)	TCK frequency (debug)			TBC	MHz	
f(TCK_B)	TCK frequency (boundary scan)			TBC	MHz	
T(SETUP)	TDO to TCK setup time	TBC			ns	
T(HOLD)	TDO to TCK hold time	TBC			ns	A
T(DELAY)	TCK to output delay			TBC	ns	

Figure 37: JTAG timing

A Timing applies to TMS and TDI inputs.

All JTAG operations are synchronous to TCK.

0x15: Debug interrupt type

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		If the debug interrupt was caused by a hardware breakpoint or hardware watchpoint, this field contains the number of the breakpoint or watchpoint. If multiple breakpoints or watchpoints trigger at once, the lowest number is taken.
15:8	DRW		If the debug interrupt was caused by a logical core, this field contains the number of that core. Otherwise this field is 0.
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

B.17 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it countains the resource identifier.

0x16: Debug interrupt data

Bits	Perm	Init	Description
31:0	DRW		Value.

B.18 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18: Debug core control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which logical cores are stopped when not in debug mode. Every bit which is set prevents the respective logical core from running.

C.11 PC of logical core 1: 0x41

0x41: PC of logical core 1

Bits	Perm	Init	Description
31:0	RO		Value.

C.12 PC of logical core 2: 0x42

0x42: PC of logical core 2

Bits	Perm	Init	Description
31:0	RO		Value.

C.13 PC of logical core 3: 0x43

0x43: PC of logical core 3

Bits	Perm	Init	Description
31:0	RO		Value.

C.14 PC of logical core 4: 0x44

0x44: PC of logical core 4

Bits	Perm	Init	Description
31:0	RO		Value.

C.15 SR of logical core 0: 0x60

Value of the SR of logical core 0

0x60: SR of logical core 0

Bits	Perm	Init	Description
31:0	RO		Value.

D Digital Node Configuration

The digital node control registers can be accessed using configuration reads and writes (use `write_node_config_reg(device, ...)` and `read_node_config_reg(device, ...)` for reads and writes).

Number	Perm	Description
0x00	RO	Device identification
0x01	RO	System switch description
0x04	RW	Switch configuration
0x05	RW	Switch node identifier
0x06	RW	PLL settings
0x07	RW	System switch clock divider
0x08	RW	Reference clock
0x0C	RW	Directions 0-7
0x0D	RW	Directions 8-15
0x10	RW	DEBUG_N configuration
0x1F	RO	Debug source
0x20 .. 0x27	RW	Link status, direction, and network
0x40 .. 0x43	RW	PLink status and network
0x80 .. 0x87	RW	Link configuration and initialization
0xA0 .. 0xA7	RW	Static link configuration

Figure 43: Summary

D.1 Device identification: 0x00

This register contains version and revision identifiers and the mode-pins as sampled at boot-time.

Bits	Perm	Init	Description
31:24	RO	0x00	Chip identifier.
23:16	RO		Sampled values of pins MODE0, MODE1, ... on reset.
15:8	RO		SSwitch revision.
7:0	RO		SSwitch version.

0x00: Device identification

D.2 System switch description: 0x01

This register specifies the number of processors and links that are connected to this switch.

E.6 Link Control and Status: 0x80

0x80: Link Control and Status

Bits	Perm	Init	Description
31:28	RO	-	Reserved
27	RO	0	Set to 1 on error: an RX buffer overflow or illegal token encoding has been received. This bit clears on reading.
26	RO	0	1 if this end of the link has issued credit to allow the remote end to transmit.
25	RO	0	1 if this end of the link has credits to allow it to transmit.
24	WO	0	Set to 1 to initialize a half-duplex link. This clears this end of the link's credit and issues a HELLO token; the other side of the link will reply with credits. This bit is self-clearing.
23	WO	0	Set to 1 to reset the receiver. The next symbol that is detected will be assumed to be the first symbol in a token. This bit is self-clearing.
22	RO	-	Reserved
21:11	RW	1	The number of system clocks between two subsequent transitions within a token
10:0	RW	1	The number of system clocks between two subsequent transmit tokens.

E.7 1 KHz Watchdog Control: 0xD6

The watchdog provides a mechanism to prevent programs from hanging by resetting the xCORE Tile after a pre-set time. The watchdog should be periodically "kicked" by the application, causing the count-down to be restarted. If the watchdog expires, it may be due to a program hanging, for example because of a (transient) hardware issue.

The watchdog timeout is measured in 1 ms clock ticks, meaning that a time between 1 ms and 65 seconds can be set for the timeout. The watchdog timer is only clocked during the AWAKE power state. When writing the timeout value, both the timeout and its one's complement should be written. This reduces the chances of accidentally setting kicking the watchdog. If the written value does not comprise a 16-bit value with a 16-bit one's complement, the request will be NACKed, otherwise an ACK will be sent.

If the watchdog expires, the xCORE Tile is reset.

0xD6: 1 KHz Watchdog Control

Bits	Perm	Init	Description
31:16	RO	0	Current value of watchdog timer.
15:0	RW	1000	Number of 1kHz cycles after which the watchdog should expire and initiate a system reset.

0x00: ADC Control input pin 0

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.2 ADC Control input pin 1: 0x04

Controls specific to ADC input pin 1.

0x04: ADC Control input pin 1

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.3 ADC Control input pin 2: 0x08

Controls specific to ADC input pin 2.

0x08: ADC Control input pin 2

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.4 ADC Control input pin 3: 0x0C

Controls specific to ADC input pin 3.

0x0C: ADC Control input pin 3

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.5 ADC Control input pin 4: 0x10

Controls specific to ADC input pin 4.

0x10: ADC Control input pin 4

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.6 ADC Control input pin 5: 0x14

Controls specific to ADC input pin 5.

0x14: ADC Control input pin 5

Bits	Perm	Init	Description
31:8	RW	0	The node and channel-end identifier to which data for this ADC input pin should be send to. This is the top 24 bits of the channel-end identifier as allocated on an xCORE Tile.
7:1	RO	-	Reserved
0	RW	0	Set to 1 to enable this input pin on the ADC.

F.7 ADC Control input pin 6: 0x18

Controls specific to ADC input pin 6.

Figure 46: Summary

Number	Perm	Description
0x00 .. 0x7F	RW	Deep sleep memory
0xFF	RW	Deep sleep memory valid

G.1 Deep sleep memory: 0x00 .. 0x7F

128 bytes of memory that can be used to hold data when the xCORE Tile is powered down.

0x00 .. 0x7F: Deep sleep memory

Bits	Perm	Init	Description
7:0	RW		User defined data

G.2 Deep sleep memory valid: 0xFF

One byte of memory that is reset to 0. The program can write a non zero value in this register to indicate that the data in deep sleep memory is valid.

0xFF: Deep sleep memory valid

Bits	Perm	Init	Description
7:0	RW	0	User defined data, reset to 0.

H Oscillator Configuration

The *Oscillator* is peripheral 4. The control registers are accessed using 8-bit reads and writes (use `write_periph_8(device, 4, ...)` and `read_periph_8(device, 4, ...)` for reads and writes).

Figure 47: Summary

Number	Perm	Description
0x00	RW	General oscillator control
0x01	RW	On-silicon-oscillator control
0x02	RW	Crystal-oscillator control

0x00: General control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7	RW	0	By default, when waking up, the voltage levels stored in the LEVEL CONTROL registers are used. Set to 1 to use the power-on voltage levels.
6	WO		Set to 1 to re-apply the current contents of the AWAKE state. Use this when the program has changed the contents of the AWAKE state register. Self clearing.
5	RW	0	Set to 1 to use a 64-bit timer.
4	RW	0	Set to 1 to wake-up on the timer.
3	RW	1	If waking on the WAKE pin is enabled (see above), then by default the device wakes up when the WAKE pin is pulled high. Set to 0 to wake-up when the WAKE pin is pulled low.
2	RW	0	Set to 1 to wake-up when the WAKE pin is at the right level.
1	RW	0	Set to 1 to initiate sleep sequence - self clearing. Only set this bit when in AWAKE state.
0	RW	0	Sleep clock select. Set to 1 to use the default clock rather than the internal 31.25 kHz oscillator. Note: this bit is only effective in the ASLEEP state.

J.2 Time to wake-up, least significant 32 bits: 0x04

This register stores the time to wake-up. The value is only used if wake-up from the real-time clock is enabled, and the device is asleep.

0x04: Time to wake-up, least significant 32 bits

Bits	Perm	Init	Description
31:0	RW	0	Least significant 32 bits of time to wake-up.

J.3 Time to wake-up, most significant 32 bits: 0x08

This register stores the time to wake-up. The value is only used if wake-up from the real-time clock is enabled, if 64-bit comparisons are enabled, and the device is asleep. In most cases, 32-bit comparisons suffice.

0x18: Power supply states whilst AWAKE

Bits	Perm	Init	Description
31:15	RO	-	Reserved
14	RW	0	Set to 1 to disable clock to the xCORE Tile.
13:10	RO	-	Reserved
9	RW	0	Sets modulation used by DCDC2: 0: PWM modulation (max 475 mA) 1: PFM modulation (max 50 mA)
8	RW	0	Sets modulation used by DCDC1: 0: PWM modulation (max 700 mA) 1: PFM modulation (max 50 mA)
7:6	RO	-	Reserved
5	RW	1	Set to 1 to enable VOUT6 (IO supply).
4	RW	1	Set to 1 to enable LDO5 (core PLL supply).
3:2	RO	-	Reserved
1	RO	1	Set to 1 to enable DCDC2 (analogue supply).
0	RW	1	Set to 1 to enable DCDC1 (core supply).

J.8 Power supply states whilst SLEEPING1: 0x1C

This register controls what state the power control block should be in when in the SLEEPING1 state. It also defines the time that the system shall stay in this state.

Bits	Perm	Init	Description
31:21	RO	-	Reserved
20:16	RW	16	Log2 number of cycles to stay in this state: 0: 1 clock cycles 1: 2 clock cycles 2: 4 clock cycles ... 31: 2147483648 clock cycles
15	RO	-	Reserved
14	RW	0	Set to 1 to disable clock to the xCORE Tile.
13:10	RO	-	Reserved
9	RW	0	Sets modulation used by DCDC2: 0: PWM modulation (max 475 mA) 1: PFM modulation (max 50 mA)
8	RW	0	Sets modulation used by DCDC1: 0: PWM modulation (max 700 mA) 1: PFM modulation (max 50 mA)
7:6	RO	-	Reserved
5	RW	1	Set to 1 to enable VOUT6 (IO supply).
4	RW	0	Set to 1 to enable LDO5 (core PLL supply).
3:2	RO	-	Reserved
1	RO	1	Set to 1 to enable DCDC2 (analogue supply).
0	RW	0	Set to 1 to enable DCDC1 (core supply).

0x1C: Power supply states whilst SLEEPING1

J.9 Power supply states whilst SLEEPING2: 0x20

This register controls what state the power control block should be in when in the SLEEPING2 state. It also defines the time that the system shall stay in this state.

0x40: LDO5 level control

Bits	Perm	Init	Description
31:3	RO	-	Reserved
2:0	RW	pin	The required voltage in 100 mV steps: 0: 0.6V 1: 0.7V 2: 0.8V ... 6: 1.2V 7: 1.3V

K XMOS USB Interface

XMOS provides a low-level USB interface for connecting the device to a USB transceiver using the UTMI+ Low Pin Interface (ULPI). The ULPI signals must be connected to the pins named in Figure 50. Note also that some ports on the same tile are used internally and are not available for use when the USB driver is active (they are available otherwise).

Pin	Signal
X*n*D02	Unavailable when USB active
X*n*D03	
X*n*D04	
X*n*D05	
X*n*D06	
X*n*D07	
X*n*D08	
X*n*D09	

Pin	Signal
X*n*D12	ULPI_STP
X*n*D13	ULPI_NXT
X*n*D14	ULPI_DATA[0]
X*n*D15	ULPI_DATA[1]
X*n*D16	ULPI_DATA[2]
X*n*D17	ULPI_DATA[3]
X*n*D18	ULPI_DATA[4]
X*n*D19	ULPI_DATA[5]
X*n*D20	ULPI_DATA[6]
X*n*D21	ULPI_DATA[7]
X*n*D22	ULPI_DIR
X*n*D23	ULPI_CLK

Pin	Signal
X*n*D26	Unavailable when USB active
X*n*D27	
X*n*D28	
X*n*D29	
X*n*D30	
X*n*D31	
X*n*D32	
X*n*D33	

X*n*D37	Unavailable when USB active
X*n*D38	
X*n*D39	
X*n*D40	
X*n*D41	
X*n*D42	
X*n*D43	

Figure 50: ULPI signals provided by the XMOS USB driver

L Device Errata

This section describes minor operational differences from the data sheet and recommended workarounds. As device and documentation issues become known, this section will be updated the document revised.

To guarantee a logic low is seen on the pins DEBUG_N, MODE[4:0], TMS, TCK and TDI, the driving circuit should present an impedance of less than 100 Ω to ground. Usually this is not a problem for CMOS drivers driving single inputs. If one or more of these inputs are placed in parallel, however, additional logic buffers may be required to guarantee correct operation.

For static inputs tied high or low, the relevant input pin should be tied directly to GND or VDDIO.